DOCUMENT CHANGE REQUEST

DCR number	273	Changes required for: General	Originator: S Thacker
Date: 2006/07/24		Date sent: 2006/07/24	Organisation: ESA/ESTEC
Status: IMPLEMENTED			

Title:	Requirements for Lead Materials and Finishes for Components for Space Application		
Number:	23500	Issue:	2

Other documents affected:

Page:

p6: para 3.2
p7, 8, 9: para 3.3 & para 3.3 note 2 & 6

Paragraph:

p6: para 3.2
p7, 8, 9: para 3.3 & para 3.3 note 2 & 6

Original wording:

Proposed wording:

See attached mark-up for details.

The addition of a new terminal material Sn10/Pb90 and the applicable requirements as follows:

Para 3.2 add new material 'R' Tin-Lead alloy Sn10/Pb90
Para 3.3 include new material 'R' against finish type 1 (= No finish)
Para 3.3 Note 2, include 'Tin-Lead material' in note about testing in inert atmosphere
Para 3.3 note 6, include new material 'R' with finish type 1 against assembly method 'S' (Solder)

Justification:

This material (High temperature solder) is employed by Manufacturer Atmel in various Column Grid Array (CGA) packages to function as terminals.

Attachments:
DCR_attachment_for_23500.pdf, null
Modifications:
N/A
Approval signature:
Date signed:
2006-07-24

MARK-up FOR
DCR
S. Thalle.
19/7/2006.

ESCC
European Space Components Coordination

Pages 1 to 11

REQUIREMENTS FOR LEAD MATERIALS AND FINISHES FOR COMPONENTS FOR SPACE APPLICATION

ESCC Basic Specification No. 23500

July 2006

Issue ~~2~~ 3	August 2005

esa

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DOCUMENTATION CHANGE NOTICE

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DCR No.	CHANGE DESCRIPTION
~~165~~	Specification up issued to incorporate editorial and technical changes per DCR.

See Helga for Number.

Type	Description
A	Copper (oxygen-free) electrolytic
B	Copper (electrolytic tough pitch)
C	Iron-Nickel Alloy, copper-clad (e.g. Dumet)
D	Iron-Nickel-Cobalt Alloy (e.g. Kovar, Nilo K or Dilver)
E	Nickel
F	Iron-Nickel Alloy (Alloy 52)
G	Iron-Nickel Alloy (Alloy 42)
H	Copper-core, Iron-Nickel Alloy 52, Clad-ratio 3:1
I	Copper-core, Iron-Nickel Alloy 52, Clad-ratio 1.7:1
J	Iron-core, Copper-clad Wire CCFE 30
K	Iron-core, Copper-clad Wire CCFE 70
L	Steel, Copper-clad
M	Beryllium Copper
N	Phosphor Bronze
O	Silver of purity 98% or better
P	Copper Alloy > 97% Cu (Alloy K50 or K65)
Q	Copper-Tungsten Alloy (15% Cu, 85% W)

NOTES:

The terminal material for chip carrier packages need not be from the above list and does not need to be specified in the Detail Specification.

3.3 FINAL FINISH

The final finish of leads and terminals shall conform to one of the following, as appropriate and as specified:

R	Tin-Lead Alloy Sn10/Pb90 (10% Sn, 90% Pb)

Type	Description
1	No finish. To be supplied without external finish. This is permitted only for Types A, B, C, J, K, L ~~and~~, O and R
2	Gold plating, electro-deposited. The gold plating shall be of the type which is 99.7% gold minimum. The thickness of ~~the gold plating~~ shall be 1.3μm minimum to 5.7μm maximum. Electrolytic nickel underplating is required for lead and terminal Types D, F, G, H and I in accordance with Note 3.
3	Tin-Lead plating. The tin-lead plating shall be in accordance with the best commercial practice and have a composition of 30 to 70% tin (remainder lead). The thickness shall be minimum 2.5μm to maximum 13μm.
4	Hot solder dip. The solder shall be composition Sn63 and the coating shall have a thickness of 2.5μm to 13μm. Hot solder dip may be used over final finish Type 2, 7, 8 or 12 gold plating, but prior to this the leads or terminals shall be de-golded using the procedure defined in Para. 4.3(a) of this document.
5	Nickel-plating, electro-deposited. The nickel-plating finish shall have a thickness of 1.3μm minimum to 3.8μm maximum.
6	Gold-plating, electro-deposited with Nickel and Copper underplating. The first layer to be applied shall be 10 to 14μm of electro-deposited copper. The second layer to be applied shall be 3 to 6μm of electro-deposited nickel. The final layer to be applied shall be Type 2 gold plating.
7	Gold plating, electro-deposited with electroless Nickel underplating. This shall have an underlayer of nickel, electroless deposited with a 2 to 4μm thickness. The final layer shall be gold plating with 99.7% gold minimum. The thickness of the gold plating shall be 0.7μm minimum to 5.7μm maximum.
8	Gold plating, electro-deposited with Nickel and Palladium underplating. The first layer to be applied shall be 1.75μm minimum of electro-deposited nickel. The second layer to be applied shall be 0.25μm minimum of electro-deposited palladium. The final layer shall be gold plating with 99.7% gold minimum. The thickness of the gold plating shall be 0.7μm minimum to 5.7μm maximum.
9	Hot solder dip with Nickel underplating. This shall have an underlayer of nickel, electroless deposited with a 2 to 5μm thickness. The final layer shall be hot solder dip in accordance with Type 4.
10	Silver plating, electro-deposited. The plating shall be of 98% minimum silver purity of thickness between 3.8 and 8.9μm.
11	Reflowed Tin-Lead plating, with Nickel and Silver underplating. The first layer to be applied shall be 2μm minimum of electro-deposited nickel. The second layer to be applied shall be 0.1μm minimum of electro-deposited silver. The final layer to be applied shall be reflowed electro-deposited tin-lead plating with a composition of 85 to 95% tin (remainder lead). The thickness of the tin-lead plating shall be 3μm minimum to 8μm maximum.

Type	Description
12	Gold plating, electro-deposited, with Nickel and Silver underplating. The first layer to be applied shall be 2μm minimum of electro-deposited nickel. The second layer to be applied shall be 0.1μm minimum of electro-deposited silver. The final layer shall be 99.7% minimum gold plating. The thickness of the gold plating shall be 0.7μm minimum to 5.7μm maximum.
13	Gold plating, electro-deposited, with Copper underplating. The first layer to be applied shall be 5μm minimum of copper. The final layer shall be 99.7% minimum gold plating. The thickness of the gold plating shall be 2.5μm minimum to 5.7μm maximum.
14	Gold plating, electro-deposited with electrolytic Nickel underplating. This shall have an underlayer of nickel, electro-deposited with 2 to 9μm thickness. The final layer shall be gold-plating with 99.7% gold minimum. The thickness of the gold-plating shall be 0.7μm minimum to 5.7μm maximum
15	Tin-lead plating, electro-deposited with Silver underplating. The first layer shall be a nominal 0.1μm of electro-deposited silver. The final layer to be applied shall be electro-deposited tin-lead plating with a composition of 85 to 95% tin. The thickness of the tin-lead plating shall be 5 to 10μm.

NOTES:

1. The final finish on a lead or terminal shall commence within 0.2mm of the device body, glass or metal seal or the lower end of the lead frame brazed joint. For epoxy sealed devices, the final finish shall commence not more than 1.5mm from the encapsulant.

2. Tin-lead, Tin-lead plated or solder-dipped lead and terminal material and finish may only be tested in normal atmosphere at $T_{amb} \leq +125°C$. Where tests are performed at $T_{amb} > +125°C$, a100% inert atmosphere must be used and components which are so tested shall include a warning paragraph or note to this effect in Section 1 of the Detail Specification.

3. An underplating of nickel is required prior to the Type 2 gold-plated final finish on leads or terminals of Type D, F, G, H and I.
   The thickness of leads and terminals procured with underplating shall be specified in the Manufacturer's procurement specification. When the underplating is performed by the Manufacturer, or his Sub-contractor, the underplating thickness shall be specified in his/the Subcontractor's process specification. The thickness of nickel shall be:

   (a) 0.5μm minimum to 3μm maximum.
   (b) 1.3μm minimum to 3.8μm maximum.

4. All plating, whether for final finish or underplating, shall be deposited in such a manner that the plating is applied on clean, non-oxidized metal surfaces. The overall plating(s) shall be ductile such that when a plated lead or terminal is bent over a radius equal to twice the total lead or terminal thickness, there shall be no cracking and/or delamination of the plating layer visible at a magnification of X8.
   All electroless-nickel plating shall have a bend test performed, on a sample basis, as part of the final inspection to ensure that this plating is sufficiently ductile as to avoid cracking or delamination during later operations when stress relief bends are being performed. The inside radius of the bend shall be equal to the lead or terminal diameter or thickness.

5. Pure Tin finish with more than 98% tin purity is not acceptable due to the possibility of whisker

growth and transformation to grey tin powder at low temperature.

6. Combinations of material and finish types together with the appropriate assembly methods are as follows:

Material Type	Finish Type														
	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15
A	W	S W	S	S	S W	S W	S W	S W	S	S W	S	S W	S W	S W	-
B	W	-	S	S	S W	S W	S W	S W	S	S W	S	S W	S W	S W	-
C	W	S W	S	S	S W	S W	S W	S W	S	S W	S	S W	S W	S W	-
D	-	S W	S	S	S W	S W	S W	S W	S	S W	S	S W	-	S W	-
E	-	S W	S	S	S W	S W	S W	S W	S	S W	S	S W	S W	S W	-
F	-	S W	S	S	S W	S W	S W	S W	S	S W	S	S W	-	S W	-
G	-	S W	S	S	S W	S W	S W	S W	S	S W	S	S W	-	S W	-
H	-	S W	S	S	S W	S W	S W	S W	S	S W	S	S W	-	S W	-
I	-	S W	S	S	S W	S W	S W	S W	S	S W	S	S W	-	S W	-
J	-	S W	S	S	S W	S W	S W	S W	S	S W	S	S W	S W	S W	-
K	-	S W	S	S	S W	S W	S W	S W	S	S W	S	S W	S W	S W	-
L	-	S W	S	S	S W	S W	S W	S W	S	S W	S	S W	S W	S W	-
M	-	S W	S	S	S W	S W	S W	S W	S	S W	S	S W	S W	S W	-
N	-	S W	S	S	S W	S W	S W	S W	S	S W	S	S W	S W	S W	-
O	S W	-	-	S	-	-	-	-	-	-	-	-	-	-	-
P	-	-	-	-	-	-	-	-	-	-	-	-	-	-	S
Q	-	-	-	-	-	-	-	-	-	-	-	-	-	S	-
R	S	-	-	-	-	-	-	-	-	-	-	-	-	-	-

Legend: S = Solder, W = Weld.

4. ADDITIONAL REQUIREMENTS

4.1 CONDUCTIVE EPOXIES

Conductive epoxies will be considered for use as terminations on a case-by-case basis.

4.2 SUBSTITUTION OF LEAD OR TERMINAL TYPES

Substitution of any type of lead or terminal for the existing leads or terminals on an ESCC qualified component shall not take place without prior determination of the effect of such substitution on the component quality and reliability.

The approval of the ESCC Executive must always be obtained before any such substitution is implemented.

4.3 DE-GOLDING AND APPLICATION OF FINAL FINISH FOR TYPE 4

When a Type 4 finish is specified and is produced from a lead or terminal which was initially gold-plated, the gold shall be removed and the final finish applied using the following procedure: